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PVA TePla GIGA 690 MICROWAVE PLASMA SYSTEM SN 02592 Vintage 2013

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The Plasma System GIGA 690 is a state-of-the-art plasma processing equipment. It is a PCcontrolled production tool, featuring all options of data communication, and moreover, it is the most versatile plasma cleaning system in the world of chip packaging.

Featuring electrode-free energy feeding and plasma generation, the GIGA 690 system delivers unsurpassed flexibility. This electrode-free power coupling is key to the treatment of substrates in closed, non-slotted magazines in the downstream process.

Slotted magazines are processed perfectly on a rotating platform.

In addition, the ECR mode is an extra function of this plasma system.

PVA TePla's unique microwave plasma processing technology serves a broad spectrum of applications including plasma cleaning before wire bond, mold and solder ball attach, as well as plasma cleaning and activation prior to Flip Chip underfill and undermold.

Our process capability upgrade, introducing pure H2, is one more decisive benefit. It provides e.g. unparalleled cleaning performance prior to wire bonding by removing oxide layers, sulphur residues or other inorganic impurities (H2 safety certificate available).

As a most modern production tool, the Microwave Plasma System GIGA 690 provides high throughput and serves the full range of chip packaging applications.

The system is featuring a highly attractive graphical user interface and is programmed with an easily mastered operating platform. The Plasma System GIGA 690 is available with a hinged or sliding-type door design.

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